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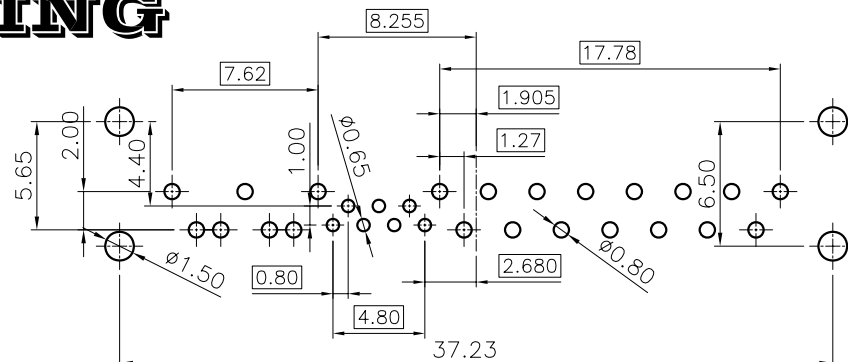
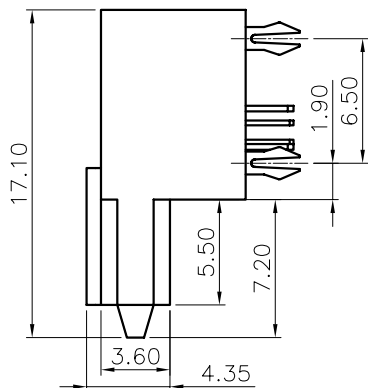
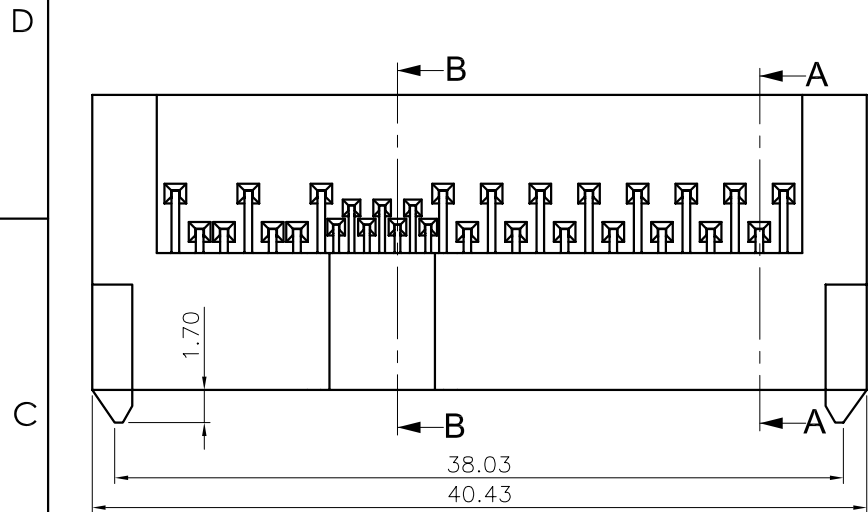
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PART NO. SEE TABLE

REVISIONS			
LTR	DESCRIPTION	Drawing	DATE
A	新產品發行圖面	GARY	01/15/08

# CUSTOMER DRAWING



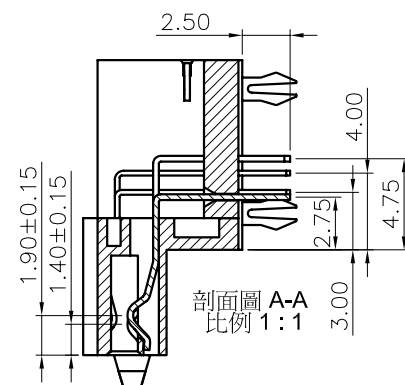
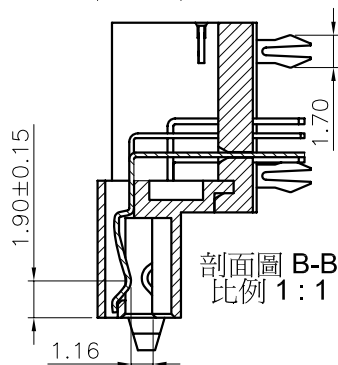
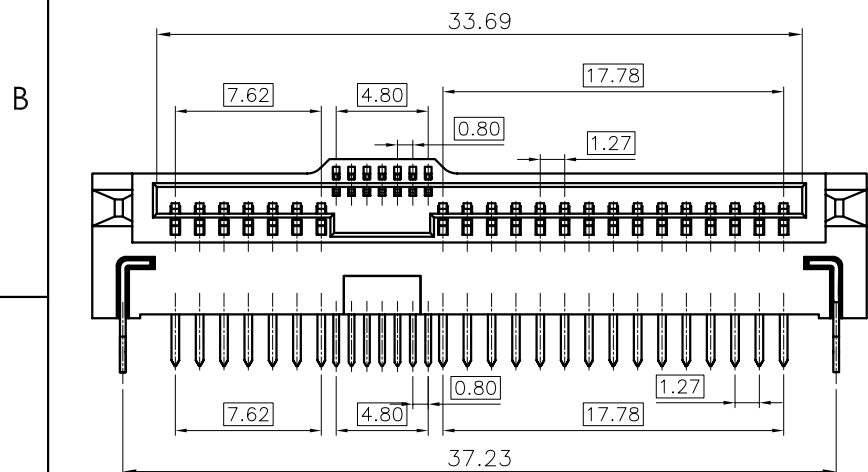
RECOMMENDED PCB LAYOUT

TABLE

020-01-00338	15 U" GOLD	LCP BLACK	GP
PART NO.	PLATED	PLASTIC&COLOR	NOTE

NOTE:

- MATERIAL :  
BASE : HIGH TEMPERATURE THERMOPLASTIC UL94V-0,  
TERMINAL(MAX):COPPER ALLOY,THICKNESS = 0.30 mm  
TERMINAL(MIN):COPPER ALLOY,THICKNESS = 0.25 mm  
FORKLOCK:BRASS THICKNESS = 0.30 mm
- PLATING:  
CONTACT:GOLD OVER 50u" MIN NICKEL UNDERPLATE  
SOLDER TAIL:150u"MIN MISTY TIN 50u" MIN NICKEL UNDERPLATE  
GOLD SPECIFICATION:SEE TABLE
- ELECTRONICAL SPECIFICATION:  
CURRENT RATING: 1.5 AMPERE PER CONTACT  
CONTACT RESISTANCE: 30 MILLIOHMS MAX.  
INSULATION RESISTANCE: 1000 MEGOHMS MIN.  
DIELECTRIC WITHSTANDING VOLTAGE: 500 VAC.  
OPERATING TEMPERATURE: -40°C~+85°C



DIMENSION ARE MILLIMETERS TOLERANCES ARE : DECIMALS .X ± 0.20 .XX ± 0.15 ANGLE: X ± 3°	APPROVALS		DATE	TITLE: SAS 29PIN 加寬型兩排DIP
	DRAWN	GARY	01/15/08	
CHECKED				
APPROVALS				
SIZE mm	SCALE : 1 : 1	DRAWING NO. 000581	REV. A	
ID. NO. XXXXXXXXX	SHEET 1 OF 1			

DESCRIPTION

QTY

UNIT

DO NOT SCALE DRAWING

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